

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6854031

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SEONG GUK SON	04/27/2021
HYUCK MIN KWON	04/27/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HYUNDAI MOTOR COMPANY
<b>Street Address:</b>	12, HEOLLEUNG-RO, SEOCHO-GU
<b>City:</b>	SEOUL
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	06797
<b>Name:</b>	KIA CORPORATION
<b>Street Address:</b>	12, HEOLLEUNG-RO, SEOCHO-GU
<b>City:</b>	SEOUL
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	06797
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17380829
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	ejasinska@lsk-iplaw.com, docket-us@lsk-iplaw.com
<b>Correspondent Name:</b>	LEMPIA SUMMERFIELD KATZ LLC (HMC/KMC)
<b>Address Line 1:</b>	20 SOUTH CLARK STREET
<b>Address Line 2:</b>	SUITE 600
<b>Address Line 4:</b>	CHICAGO, ILLINOIS 60603
<b>ATTORNEY DOCKET NUMBER:</b>	010300-21026A
<b>NAME OF SUBMITTER:</b>	BRYAN J. LEMPIA
<b>SIGNATURE:</b>	/Bryan J. Lempia/
<b>DATE SIGNED:</b>	08/09/2021

	This document serves as an Oath/Declaration (37 CFR 1.63).
--	--

**Total Attachments: 2**

source=HMC-20409US\_AssignmentDeclaration as recorded#page1.tif

source=HMC-20409US\_AssignmentDeclaration as recorded#page2.tif

**ASSIGNMENT - STATEMENT**

As a below named inventor, I hereby declare that this DECLARATION is directed to the invention(s) described in an application for United States patent entitled:

**ELECTRODE FOR RESISTANCE SPOT WELDING AND DEVICE FOR RESISTANCE SPOT WELDING INCLUDING THE SAME**

The specification of which is attached hereto.

The above-identified application was made or authorized to be made by me.

I believe that I am an original joint inventor of a claimed invention in the application.

I hereby state that I have reviewed and understand the contents of the above identified application.

I acknowledge my duty to disclose to the United States Patent and Trademark Office all information that I know to be material to patentability as defined in 37 C.F.R. §1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, SON, Seong Guk and KWON, Hyuck Min, hereinafter called the "Assignors", have made the invention described in the above identified application, executed by Assignors on the same date as this Assignment;

WHEREAS, HYUNDAI MOTOR COMPANY and KIA CORPORATION, hereinafter called the "Assignees", desire to acquire the entire right, title and interest in and to the invention(s) and the patent application identified above, and all patents which may be obtained for said invention(s), as set forth below. The Assignors acknowledge that the above Case No., Docket No., Serial No., and/or filing date of the patent application may be added after execution of this Assignment, as needed and when said information becomes known or available;

NOW, THEREFORE, for what is mutually agreeable to be valuable and legally sufficient consideration, the receipt of which by the Assignors from the Assignees is hereby acknowledged, the Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer to the Assignee, the entire right, title and interest for the United States in and to the invention(s) and the patent application identified above, and any patents that may issue for said invention(s) in the United States; together with the entire right, title and interest in and to said invention(s) and all patent applications and patents issuing therefrom in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; together with the entire right, title and interest in and to all continuations, divisions, renewals and extensions of any of the patent applications and patents defined above; together with the right to recover all damages, including, but not limited to, a reasonable royalty, by reason of past, present, or future infringement or any other violation of patent or patent application rights; to have and to hold for the sole and exclusive use and benefit of the Assignees, their successors and assigns, to the full end of the term or terms for all such patents.

Hyundai Counsel Case No.: HMC-20409/US

Atty. Docket No.: 010300-21026A

U.S. Application Serial No.: 17/380,829

Appl. Filing Date: July 20, 2021

THE ASSIGNORS HEREBY COVENANT AND AGREE, for both the Assignors and the Assignors' legal representatives, that the Assignors will assist the Assignees in the prosecution of the patent application identified above; in the making and prosecution of any other patent applications that the Assignees may elect to make covering the invention(s) identified above; in vesting in the Assignees like exclusive title in and to all such other patent applications and patents; and in the prosecution of any interference, reissue, reexamination, opposition, or other such proceeding before the U.S Patent and Trademark Office which may arise involving said invention(s), or any such patent application or patent; and that the Assignors will execute and deliver to the Assignee any and all additional papers which may be requested by the Assignees to carry out the terms of this Assignment. The Commissioner of Patents and Trademarks is hereby authorized and requested to issue patents to the Assignees in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the Assignors/Inventors have executed this Assignment-Statement.

손성국

April 27, 2021

(First Inventor/Assignor Signature)

(Date)

SON, Seong Guk

(First Inventor/Assignor Name)

권혁민

April 27, 2021

(Second Inventor/Assignor Signature)

(Date)

KWON, Hyuck Min

(Second Inventor/Assignor Name)